

DETAILED ACTION

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 12/29/09 has been entered.

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. Edwin Garlepp (Reg. No. 45,330) on 10/21/09.

The application has been amended as follows:

1) For a specification:

Please, change the title from "MULTILAYERED PRINTED CIRCUIT BOARD, SOLDER RESIST COMPOSITION, MULTILAYERED PRINTED CIRCUIT BOARD MANUFACTURING METHOD, AND SEMICONDUCTOR DE:VICE" to - -

MULTILAYERED PRINTED CIRCUIT BOARD - - .

2) For the claims:

Claim 9 (Twice Currently-Amended): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and

a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component provided within resin and comprising at least a thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer; **and**

wherein the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of a resin,

the resin is hardened by curing, and

the solder resist layer further comprises an inorganic filler.

Claim 36 (Twice Currently-Amended): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and

a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component provided within of a resin and comprising at least a thermosetting resin, said elastomer component is at least one member selected

from the group consisting of natural rubber, synthetic rubber, a thermoplastic resin and thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer; and

wherein the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of a resin, the resin is hardened by curing, and the solder resist layer further comprises an inorganic filler.

3) Cancel claims 41-50 without prejudice or terminal disclaimer.

Allowable Subject Matter

2. Claims 9, 32, 34, 36, and 39-40 are allowed (renumber claims are 1-6).

The following is an examiner's statement of reasons for allowance: in response to remarks and claimed amendments made in Applicant's Amendment filed on 09/23/09 and a Personal Interview on 10/21/09, applicant's arguments are persuasive. Amended claims have been considered and upon conclusion of a comprehensive search of the prior arts. The Office indicates that the claims, as amended, are allowable.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lee Jinhee can be reached on 571-272-1977. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Tuan T Dinh/
Primary Examiner, Art Unit 2841.